

### NTR1P02L, NVTR01P02L

### **Power MOSFET**

# -20 V, -1.3 A, P-Channel SOT-23 Package

These miniature surface mount MOSFETs low  $R_{DS(on)}$  assure minimal power loss and conserve energy, making these devices ideal for use in space sensitive power management circuitry. Typical applications are DC–DC converters and power management in portable and battery–powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

#### **Features**

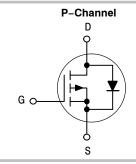
- Low R<sub>DS(on)</sub> Provides Higher Efficiency and Extends Battery Life
- Miniature SOT-23 Surface Mount Package Saves Board Space
- NVTR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Pb-Free and Halide-Free Packages are Available

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Symbol	Value	Unit
$V_{DSS}$	-20	V
$V_{GS}$	±12	V
I <sub>D</sub> I <sub>DM</sub>	-1.3 -4.0	A A
P <sub>D</sub>	400	mW
T <sub>J</sub> , T <sub>stg</sub>	– 55 to 150	°C
$R_{\theta JA}$	300	°C/W
T <sub>L</sub>	260	°C
	$\begin{array}{c} V_{DSS} \\ V_{GS} \\ \end{array}$ $\begin{array}{c} I_{D} \\ I_{DM} \\ \end{array}$ $\begin{array}{c} P_{D} \\ \end{array}$ $T_{J}, T_{stg} \\ \end{array}$ $R_{\theta JA}$	V <sub>DSS</sub> -20 V <sub>GS</sub> ±12  I <sub>D</sub> -1.3 I <sub>DM</sub> -4.0  P <sub>D</sub> 400  T <sub>J</sub> , T <sub>stg</sub> -55 to 150  R <sub>θJA</sub> 300

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

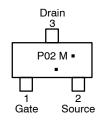
V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> Max	I <sub>D</sub> Max
-20 V	220 mΩ @ -4.5 V	–1.3 A



## MARKING DIAGRAM & PIN ASSIGNMENT



SOT-23 CASE 318 STYLE 21



P02 = Specific Device Code

M = Date Code\*
■ Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTR1P02LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
NTR1P02LT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel
NVTR01P02LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



# NTR1P02L, NVTR01P02L

#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Parameter	Test Condition	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•			•	•	
Drain-to-Source Breakdown Voltage	$(V_{GS} = 0 \text{ V}, I_D = -10 \mu\text{A})$	V <sub>(BR)DSS</sub>	-20			V
Zero Gate Voltage Drain Current	$(V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V})$ $(V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V},$ $T_{J} = 125^{\circ}\text{C})$	I <sub>DSS</sub>			-1.0 -10	μΑ
Gate-Body Leakage Current	$(V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V})$	I <sub>GSS</sub>			±100	nA
TY CHARACTERISTICS (Note 1)	-			-	-	-
Gate Threshold Voltage	$(V_{DS} = V_{GS}, I_D = -250 \mu A)$	V <sub>GS(th)</sub>	-0.7	-1.0	-1.25	V
Static Drain-to-Source On-Resistance	$(V_{GS} = -4.5 \text{ V}, I_D = -0.75 \text{ A})$ $(V_{GS} = -2.5 \text{ V}, I_D = -0.5 \text{ A})$	r <sub>DS(on)</sub>		0.140 0.200	0.22 0.35	Ω
DYNAMIC CHARACTERISTICS				•	•	
Input Capacitance	(V <sub>DS</sub> = -5.0 V)	C <sub>iss</sub>		225		pF
Output Capacitance	(V <sub>DS</sub> = -5.0 V)	C <sub>oss</sub>		130		1
Transfer Capacitance	(V <sub>DS</sub> = -5.0 V)	$(V_{DS} = -5.0 \text{ V})$ $C_{rss}$		55		
SWITCHING CHARACTERISTICS	Note 2)					
Turn-On Delay Time		t <sub>d(on)</sub>		7.0		ns
Rise Time	$(V_{GS} = -4.5 \text{ V}, V_{DD} = -5.0 \text{ V}, I_{D} = -1.0 \text{ A}, R_{L} = 5.0 \Omega,$	t <sub>r</sub>		15		
Turn-Off Delay Time	$R_{G} = 6.0 \Omega$	t <sub>d(off)</sub>		18		
Fall Time	7	t <sub>f</sub>		9		
Total Gate Charge	$(V_{DS} = -16 \text{ V}, I_{D} = -1.5 \text{ A}, V_{GS} = -4.5 \text{ V})$	Q <sub>T</sub>		3.1		nC
SOURCE-DRAIN DIODE CHARA	CTERISTICS			•	•	
Continuous Current		I <sub>S</sub>			-0.6	Α
Pulsed Current		I <sub>SM</sub>			-0.75	
Forward Voltage (Note 2)	$(V_{GS} = 0 \text{ V}, I_{S} = -0.6 \text{ A})$	$V_{SD}$			-1.0	V
Reverse Recovery Time		t <sub>rr</sub>		16		ns
	$(I_S = -1.0 \text{ A}, V_{GS} = 0 \text{ V}, \\ dI_S/dt = 100 \text{ A}/\mu\text{s})$	ta		11		1
	αι5/αι = 100 / γμο)	t <sub>b</sub>		5.5		
Reverse Recovery Stored Charge		Q <sub>RR</sub>		8.5		nC

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperature.